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Resistive random access memory structure and fabricating method of the same

Abstract

An RRAM structure includes a substrate. A transistor is disposed on the substrate, wherein the transistor includes a gate structure, a source and a drain. An interlayer dielectric layer covers the transistor. A drain contact plug is disposed within the interlayer dielectric layer and contacts the drain, and wherein an end of the drain contact plug protrudes from the interlayer dielectric layer. A metal interlayer dielectric layer is disposed on and contacts the interlayer dielectric layer. A resistive random access memory (RRAM) is disposed on the drain and within a first trench in the metal interlayer dielectric layer, wherein the RRAM includes a bottom electrode, a metal oxide layer and a top electrode, the drain contact plug contacts the bottom electrode, the bottom electrode contacts the metal oxide layer and the top electrode contacts the metal oxide layer. A metal layer is disposed within the first trench.

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Background/Summary

CROSS REFERENCE TO RELATED APPLICATIONS (1) This application is a continuation-in-part of U.S. application Ser. No. 17/541,226, filed on Dec. 2, 2021. The content of the application is incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

(1) The present invention relates to a variable resistance memory (RRAM) structure and a fabricating method of the same, and more particularly to a structure where the RRAM structure is arranged in the first metal layer (metal one level) of the local interconnection in the back end of line.

2. Description of the Prior Art

(2) RRAM is a type of non-volatile memory that has the advantages of small memory cell size, ultra-high-speed operation, low-power operation, high endurance, and compatibility with CMOS.

(3) The main operating principle of RRAM is to change the resistance of the metal oxide by applying bias voltage so as to store data. The data stored in RRAM is read by detecting different resistances in each of RRAMs.

(4) Traditionally, RRAM is inserted in the position of the via, one of the local interconnection in

the back-end process. However, by doing so, the top surface of the via one which has RRAM inserted therein becomes uneven, and shifts from the original design position. Therefore, it is necessary to use an additional planarization process to smooth the top surface of RRAM to keep the top surface of the via at the original design position.

SUMMARY OF THE INVENTION

(5) In light of the above, the present invention provides a new method of manufacturing an RRAM structure, which prevents the RRAM from affecting the original horizontal position of the local interconnection without using any additional planarization process.

(6) According to a preferred embodiment of the present invention, a resistive random access memory structure includes a substrate. A transistor is disposed on the substrate, wherein the transistor includes a gate structure, a source and a drain. An interlayer dielectric layer covers the transistor. A drain contact plug is disposed within the interlayer dielectric layer and contacts the drain, and wherein an end of the drain contact plug protrudes from the interlayer dielectric layer. A metal interlayer dielectric layer is disposed on and contacts the interlayer dielectric layer. A resistive random access memory (RRAM) is disposed on the drain and within a first trench in the metal interlayer dielectric layer, wherein the RRAM includes a bottom electrode, a metal oxide layer and a top electrode, the drain contact plug contacts the bottom electrode, the bottom electrode contacts the metal oxide layer and the top electrode contacts the metal oxide layer. A metal layer is disposed within the first trench.

(7) According to another preferred embodiment of the present invention, a fabricating method of a resistive random access memory structure includes providing a substrate, wherein a first transistor is disposed on the substrate, the first transistor includes a first gate structure, a first source and a first drain, a first drain contact plug contacts the first drain, and an interlayer dielectric layer covers and contacts the substrate and the first transistor. A metal interlayer dielectric layer is formed to cover and contact the interlayer dielectric layer. Next, a first patterning process is performed to etch the metal interlayer dielectric layer and the interlayer dielectric layer to form a first trench, and wherein the first drain contact plug is exposed through the first trench, and an end of the first drain contact plug protrudes from the interlayer dielectric layer. Then, a bottom electrode material layer, a metal oxide material layer and a top electrode material layer is formed in sequence to fill in the first trench and cover the metal interlayer dielectric layer. Later, a second patterning process is performed to pattern the bottom electrode material layer, the metal oxide material layer and the top electrode material layer to form a bottom electrode, a metal oxide layer and a top electrode, wherein the top electrode, the metal oxide layer and the bottom electrode form a resistive random access memory (RRAM), and the bottom electrode contacts the first drain contact plug.

Subsequently, a metal layer is formed to fill in the first trench and cover the metal interlayer dielectric layer and the RRAM. Finally, a planarization process is performed to remove the bottom electrode outside of the first trench, the metal oxide layer outside of the first trench, the top electrode outside of the first trench and the metal layer outside of the first trench.

(8) These and other objectives of the present invention will no doubt become obvious to those of ordinary skill in the art after reading the following detailed description of the preferred embodiment that is illustrated in the various figures and drawings.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

(1) FIG. 1 to FIG. 9 depict a fabricating method of a resistive random access memory structure according to a preferred embodiment of the present invention, wherein:

(2) FIG. 1 depicts a substrate with two transistors thereon;

(3) FIG. 2 continues from FIG. 1;

- (4) FIG. 3 continues from FIG. 2;
- (5) FIG. 4 continues from FIG. 3;
- (6) FIG. 5 depicts a top view of FIG. 4;
- (7) FIG. 6 continues from FIG. 4;
- (8) FIG. 7 depicts a top view of FIG. 6;
- (9) FIG. 8 continues from FIG. 6;
- (10) FIG. 9 continues from FIG. 8; and
- (11) FIG. 10 shows a three-dimensional view of the RRAM structure in FIG. 9.

DETAILED DESCRIPTION

(12) FIG. 1 to FIG. 9 depict a fabricating method of a resistive random access memory structure according to a preferred embodiment of the present invention, wherein FIG. 5 depicts a top view of FIG. 4, and FIG. 7 depicts a top view of FIG. 6.

(13) As shown in FIG. 1, a substrate **10** is provided. The substrate **10** is divided into a memory cell region A and a logic element region B. A first transistor **12a** and a second transistor **12b** are disposed on the substrate **10**. The first transistor **12a** is disposed within the memory cell region A, and the second transistor **12b** is disposed within the logic element region B. The first transistor **12a** includes a first gate structure **14a**, a first source **18a** and a first drain **16a**. The second transistor **12b** includes a second gate structure **14b**, a second drain **18b** and a second drain **16b**. An interlayer dielectric layer **20** covers and contacts the substrate **10**, the first transistor **12a** and the second transistor **12b**. A first drain contact plug **22a**, a first source contact plug **24a**, a second drain contact plug **22b** and a source contact plug **24b** penetrate the interlayer dielectric layer **20**. Moreover, the first drain contact plug **22a** contacts the first drain **16a**. The first source contact plug **24a** contacts the first source **18a**. The second drain contact plug **22b** contacts the second drain **16b**. The second source contact plug **24b** contacts the second source **18b**. A first gate contact plug **26a** penetrates the interlayer dielectric layer **20** to contact the first gate structure **14a**. A second gate contact plug **26b** penetrates the interlayer dielectric layer **20** to contact the second gate structure **14b**. Next, an etching stop layer **28**, a metal interlayer dielectric layer **30** and a hard mask **32** are formed in sequence to cover the interlayer dielectric layer **20**. The etching stop layer **28** preferably includes silicon oxynitride, silicon carbide nitride or silicon nitride. The metal interlayer dielectric layer **30** can be oxide such as silicon oxide. The hard mask **32** can be titanium nitride or silicon nitride.

(14) As shown in FIG. 2, the hard mask **32** is patterned. Next, a first patterning process is performed by taking the hard mask **32** after patterning as a mask to etch the metal interlayer dielectric layer **30**, the etching stop layer **28** and the interlayer dielectric layer **20** to form a first trench **36a**, a second trench **36b**, a third trench **36c** and a fourth trench **36d**. The first drain contact plug **22a** is exposed through the first trench **36a**, an end of the first drain contact plug **22a** protrudes from the interlayer dielectric layer **20** and part of the first drain contact plug **22a** is still embedded in the interlayer dielectric layer **20**. The first source contact plug **24a** is exposed through the fourth trench **36d**, an end of the first source contact plug **24a** protrudes from the interlayer dielectric layer **20** and part of the first source contact plug **24a** is still embedded in the interlayer dielectric layer **20**. The second source contact plug **24b** is exposed through the second trench **36b**, an end of the second source contact plug **24b** protrudes from the interlayer dielectric layer **20** and part of second source contact plug **24b** is still embedded in the interlayer dielectric layer **20**. The second drain contact plug **22b** is exposed through the third trench **36c**, an end of the second drain contact plug **22b** protrudes from the interlayer dielectric layer **20** and part of second drain contact plug **22b** is still embedded in the interlayer dielectric layer **20**. The first drain contact plug **22a**, the first source contact plug **24a**, the second drain contact plug **22b** and the second source contact plug **24b** are preferably tungsten, copper or other metals. In this embodiment, the first drain contact plug **22a**, the first source contact plug **24a**, the second drain contact plug **22b** and the second source contact plug **24b** are tungsten.

(15) As shown in FIG. 3, a bottom electrode material layer **37**, a metal oxide material layer **38** and

a top electrode material layer **40** are formed in sequence to conformally fill into the first trench **36a**, the second trench **36b**, the third trench **36c** and the fourth trench **36d**, and to cover the metal interlayer dielectric layer **30**. The bottom electrode material layer **37** respectively encapsulates the protruded end of the first drain contact plug **22a**, the protruded end of the first source contact plug **24a**, the protruded end of the second drain contact plug **22b** and the protruded end of the second source contact plug **24b**. The bottom electrode material layer **37** includes titanium nitride or tantalum nitride. The metal oxide material layer **38** includes tantalum oxide, hafnium oxide or titanium oxide. The top electrode material layer **40** includes titanium nitride or tantalum nitride. In this embodiment, the metal oxide material layer **38** is tantalum oxide. The top electrode material layer **40** is tantalum nitride. The metal oxide material layer **38** and the top electrode material layer **40** can be made by sputtering.

(16) Please refer to FIG. **4** and FIG. **5**. A photoresist **42** is formed to cover a memory cell predetermined region M within the first trench **36a**, expose a metal connection region N within the first trench **36a** and expose the entire logic element region B. Please refer to FIG. **4**, FIG. **6** and FIG. **7**, a second patterning process **44** is performed to pattern the bottom electrode material layer **37**, the metal oxide material layer **38** and the top electrode material layer **40** by taking the photoresist **42** as a mask to form a bottom electrode **45**, a metal oxide layer **46** and a top electrode **48**. Furthermore, during the second patterning process **44**, the bottom electrode material layer **37**, the metal oxide material layer **38** and the top electrode material layer **40** within the second trench **36b**, the third trench **36c** and within the fourth trench **36d** are removed entirely. Therefore, the ends of the first source contact plug **24a**, the second drain contact plug **22b** and the second source contact plug **24b** are protruded from the interlayer dielectric layer **20** again. The bottom electrode **45**, the metal oxide layer **46** and the top electrode **48** are located within the memory cell predetermined region M. Now, the bottom electrode **45**, the top electrode **48** and the metal oxide layer **46** form a resistive random access memory (RRAM) **100**. The first drain contact plug **22a** contacts the bottom electrode **45**. The second patterning process **44** is preferably an etching process. During the etching process of the second patterning process **44**, the hard mask **32** serves as a stop layer. After the second patterning process **44**, the photoresist **42** is removed. While removing the photoresist **42**, the top electrode **48** can protect the metal oxide layer **46** from being damaged by cleaning solution used for removing the photoresist **42**.

(17) As shown in FIG. **8**, a buffer layer **50** and a metal layer **52** are formed in sequence to fill in the first trench **36a**, the second trench **36b**, the third trench **36c** and the fourth trench **36d**, and cover the interlayer dielectric layer **20** and the RRAM **100**. The buffer layer **50** encapsulates the end of the first source contact plug **24a**, the end of the second drain contact plug **22b** and the end of the second source contact plug **24b**. As shown in FIG. **9**, a planarization process **54** is performed to remove the hard mask **32**, the bottom electrode **45**, the metal oxide layer **46**, the top electrode **48**, the buffer layer **50** and the metal layer **52** outside of the first trench **36a**, and to remove the hard mask **32**, the buffer layer **50** and the metal layer **52** outside of the second trench **36b**, the third trench **36c** and the fourth trench **36d**. Now, the metal layer **52** within the first trench **36a** serves as a bit line of the first transistor **12a**. The metal layer **52** within the fourth trench **36d** serves as a source line of the first transistor **12a**. The metal layer **52** within the second trench **36b** serves as a source line of the second transistor **12b**. The metal layer **52** within the third trench **36c** serves as a drain line of the second transistor **12b**. Now, an RRAM structure **200** of the present invention is completed.

(18) FIG. **9** depicts a RRAM structure according to a preferred embodiment of the present invention. FIG. **10** shows a three-dimensional view of the RRAM structure in FIG. **9**. In order to show the RRAM structure clearly, the inlayer dielectric layer, the metal interlayer dielectric layer and all gate contact plugs are omitted in FIG. **10**.

(19) Please refer to FIG. **9** and FIG. **10**. An RRAM structure **200** includes a substrate **10**. The substrate **10** is divided into a memory cell region A and a logic element region B. A first transistor

12a and a second transistor **12b** are disposed on the substrate **10**. The first transistor **12a** is disposed within the memory cell region A, and the second transistor **12b** is disposed within the logic element region B. Numerous shallow trench isolations **13** are disposed within the substrate **10** and at two sides of the first transistor **12a** and the second transistor **12b**. The first transistor **12a** includes a first gate structure **14a**, a first source **18a** and a first drain **16a**. The second transistor **12b** includes a second gate structure **14b**, a second drain **18b** and a second drain **16b**. An interlayer dielectric layer **20** covers and contacts the substrate **10**, the first transistor **12a** and the second transistor **12b**. A first drain contact plug **22a**, a first source contact plug **24a**, a second drain contact plug **22b** and a source contact plug **24b** penetrate the interlayer dielectric layer **20**. An end of the first drain contact plug **22a** protrudes from the interlayer dielectric layer **20**. An end of the first source contact plug **24a** protrudes from the interlayer dielectric layer **20**. An end of the second source contact plug **24b** protrudes from the interlayer dielectric layer **20**. An end of the second drain contact plug **22b** protrudes from the interlayer dielectric layer **20**. Moreover, the first drain contact plug **22a** contacts the first drain **16a**. The first source contact plug **24a** contacts the first source **18a**. The second drain contact plug **22b** contacts the second drain **16b**. The second source contact plug **24b** contacts the second source **18b**. The first gate contact plug **26a** penetrates the interlayer dielectric layer **20** to contact the first gate structure **14a**. The second gate contact plug **26b** penetrates the interlayer dielectric layer **20** to contact the second gate structure **14b**.

(20) A metal interlayer dielectric layer **30** is disposed on the first drain contact plug **22a** and covers the interlayer dielectric layer **20**. An RRAM **100** is disposed on the first drain **16a** and within a first trench **36a** within the metal interlayer dielectric layer **30**. The RRAM **100** includes the bottom electrode **45**, the metal oxide layer **46** and the top electrode **48** arranged in sequence. The first drain contact plug **22a** contacts the bottom electrode **45** of the RRAM **100**. The metal oxide layer **46** contacts the bottom electrode **45** and the top electrode **48** contacts the metal oxide layer **46**. The bottom electrode **45** encapsulates the end of the first drain contact plug **22a**. The protruding end of the first drain contact plug **22a** provides more contact area between the first drain contact plug **22a** and the bottom electrode **45**. Because higher electric field is generated around the protruding end of the first drain contact plug **22a**, the efficiency of the RRAM **100** can be increased. Furthermore, a buffer layer **50** and a metal layer **52** are disposed within the first trench **36a**. The buffer layer **50** is disposed between the metal layer **52** and top electrode **48**. The metal layer **52** and the buffer layer **50** are disposed within a fourth trench **36d** within the metal interlayer dielectric layer **30**. The buffer layer **50** within the fourth trench **36d** contacts the first source contact plug **24a**. The metal layer **52** within the first trench **36a** serves as a bit line of the first transistor **12a**. The metal layer **52** within the fourth trench **36d** serves as a source line of the first transistor **12a**.

(21) Moreover, the first trench **36a** is divided into a memory cell predetermined region M and a metal connection region N. The RRAM **100** is disposed within the memory cell predetermined region M. In other words, the bottom electrode **45**, the metal oxide layer **46** and the top electrode **48** are within the memory cell predetermined region M. However, the metal oxide layer **46** and the top electrode **48** are not within the metal connection region N, and the metal layer **52** and the buffer layer **50** are within the metal connection region N.

(22) Moreover, a second trench **36b** and a third trench **36c** are disposed within the logic element region B. The metal layer **52** and the buffer layer **50** are also disposed within the second trench **36b** and the third trench **36c**. A top surface of the metal layer **52** within the first trench **36a**, the second trench **36b**, the third trench **36c** and the fourth trench **36d** is aligned with a top surface of the metal interlayer dielectric layer **30**. Two end of the bottom electrode **45**, two ends of the metal oxide layer **46** and two ends of the top electrode **48** are aligned with the top surface of the metal interlayer dielectric layer **30**. According to a preferred embodiment of the present invention, the first drain contact plug **22a**, the first source contact plug **24a**, the second drain contact plug **22b** and the second source contact plug **24b** are preferably tungsten. The bottom electrode **45** is tantalum nitride or titanium nitride. The metal oxide layer **46** is tantalum oxide. The top electrode **48** is tantalum

nitride. However, the top electrode **48** can be made of other conductive materials such as hafnium, zirconium, aluminum, tantalum, titanium, chromium, tungsten, copper, cobalt, palladium or platinum. The metal oxide layer **46** can be hafnium oxide, aluminum oxide, lanthanum oxide, yttrium oxide or zirconium oxide.

(23) The RRAM of the present invention is arranged at the position of the first metal layer (metal one level) in the local interconnection of the back-end process. In details, the first metal layer directly contacts the source contact plug and the drain contact plug. Therefore, the fabricating process of the RRAM can be combined with the first metal layer process. The first metal layer process refers to a process of forming the metal layer in the second trench, the third trench and the fourth trench as described above. Combining with the first metal layer process, the bottom electrode, the metal oxide layer and the top electrode of the RRAM, and the metal layer in the first trench can be planarized by the planarization process in the first metal layer process. In this way, an additional planarization process is not required.

(24) Those skilled in the art will readily observe that numerous modifications and alterations of the device and method may be made while retaining the teachings of the invention. Accordingly, the above disclosure should be construed as limited only by the metes and bounds of the appended claims.

Claims

1. A resistive random access memory structure, comprising: a substrate; a transistor disposed on the substrate, wherein the transistor comprises a gate structure, a source and a drain; an interlayer dielectric layer covering and contacting the transistor; a drain contact plug disposed within the interlayer dielectric layer and contacting the drain, and wherein an end of the drain contact plug protrudes from the interlayer dielectric layer; a metal interlayer dielectric layer disposed on and contacting the interlayer dielectric layer; a resistive random access memory (RRAM) disposed on the drain and within a first trench in the metal interlayer dielectric layer, wherein the RRAM comprises a bottom electrode, a metal oxide layer and a top electrode, the drain contact plug contacts the bottom electrode, the bottom electrode contacts the metal oxide layer and the top electrode contacts the metal oxide layer; and a metal layer disposed within the first trench.
2. The resistive random access memory structure of claim 1, wherein a top surface of the metal layer is aligned with a top surface of the metal interlayer dielectric layer.
3. The resistive random access memory structure of claim 1, wherein the first trench is separated into a memory cell predetermined region and a metal connection region, the bottom electrode, the metal oxide layer and the top electrode are disposed within the memory cell predetermined region.
4. The resistive random access memory structure of claim 3, wherein the bottom electrode, the metal oxide layer and the top electrode are not within the metal connection region.
5. The resistive random access memory structure of claim 1, further comprising a second trench disposed within the metal interlayer dielectric layer, a source contact plug contacting the source and being exposed from the second trench, a buffer layer and the metal layer disposed within the second trench, and the buffer layer contacting the source contact plug.
6. The resistive random access memory structure of claim 5, wherein the source contact plug is within the interlayer dielectric layer, and an end of the source contact plug protrudes from the interlayer dielectric layer.
7. The resistive random access memory structure of claim 1, wherein the bottom electrode, the metal oxide layer and the top electrode are not within the second trench.
8. A fabricating method of a resistive random access memory structure, comprising: providing a substrate, wherein a first transistor is disposed on the substrate, the first transistor comprises a first gate structure, a first source and a first drain, a first drain contact plug contacts the first drain, and an interlayer dielectric layer covers and contacts the substrate and the first transistor; forming a

metal interlayer dielectric layer covering and contacting the interlayer dielectric layer; performing a first patterning process to etch the metal interlayer dielectric layer and the interlayer dielectric layer to form a first trench, and wherein the first drain contact plug is exposed through the first trench, and an end of the first drain contact plug protrudes from the interlayer dielectric layer; forming a bottom electrode material layer, a metal oxide material layer and a top electrode material layer in sequence to fill in the first trench and cover the metal interlayer dielectric layer; performing a second patterning process to pattern the bottom electrode material layer, the metal oxide material layer and the top electrode material layer to form a bottom electrode, a metal oxide layer and a top electrode, wherein the top electrode, the metal oxide layer and the bottom electrode form a resistive random access memory (RRAM), and the bottom electrode contacts the first drain contact plug; forming a metal layer filling in the first trench and covering the metal interlayer dielectric layer and the RRAM; and performing a planarization process to remove the bottom electrode, the metal oxide layer, the top electrode and the metal layer outside of the first trench.

9. The fabricating method of a resistive random access memory structure of claim 8, further comprising: providing a second transistor disposed on the substrate, wherein the second transistor comprises a second gate structure, a second source and a second drain, the interlayer dielectric layer covers the second transistor, a second source contact plug and a second drain contact plug are disposed within the interlayer dielectric layer and respectively contact the second source and the second drain.

10. The fabricating method of a resistive random access memory structure of claim 9, further comprising: during the first patterning process, etching the metal interlayer dielectric layer and the interlayer dielectric layer to form a second trench and a third trench, wherein the second source contact plug is exposed through the second trench and the second drain contact plug is exposed through the third trench, and an end of the second source contact plug and an end of the second drain contact plug protrude from the interlayer dielectric layer; while forming the bottom electrode material layer, the metal oxide material layer and the top electrode material layer to fill in the first trench, the bottom electrode material layer, the metal oxide material layer and the top electrode material layer filling in the second trench and the third trench and the bottom electrode material layer, the metal oxide material layer and the top electrode material layer covering the metal interlayer dielectric layer; during the second patterning process, removing the bottom electrode material layer, the metal oxide material layer and the top electrode material layer within the second trench and the third trench; after the second patterning process, forming a buffer layer filling in the first trench, the second trench and the third trench; while forming the metal layer to fill in the first trench, the metal layer filling in the second trench and the third trench; and during the planarization process, removing the bottom electrode layer, the metal oxide layer, the top electrode layer, the buffer layer and the metal layer outside of the first trench, and removing the buffer layer and the metal layer outside of the second trench and the third trench.

11. The fabricating method of a resistive random access memory structure of claim 10, wherein a top surface of the metal layer, a top surface of the buffer layer, a top surface of the bottom electrode, a top surface of the metal oxide layer, a top surface of the top electrode and a top surface of the metal interlayer dielectric layer are aligned.

12. The fabricating method of a resistive random access memory structure of claim 10, wherein the first trench is separated into a memory cell predetermined region and a metal connection region, during the second patterning process, removing the bottom electrode, the metal oxide layer and the top electrode within the metal connection region, and remaining the bottom electrode, the metal oxide layer and the top electrode within the memory cell predetermined region.
